

ABSTRACT OF THE DISCLOSURE

The connection structure is obtained by electrically connecting first electrodes on a first substrate 1 and second electrodes on a second substrate with an interposed anisotropic electroconductive adhesive layer 5 so as to satisfy Eq. 1 below

$$0.5 \times \{(A^1 C^1 + A^2 C^2) / (B + C)\} \leq X \leq 2 \times \{(A^1 C^1 + A^2 C^2) / (B + C)\} \quad (1)$$

where A^1 is the height of each first electrode, B^1 is the electrode width thereof, C^1 is the width of the interelectrode space, A^2 is the height of each second electrode, B^2 is the electrode width thereof, C^2 is the width of the interelectrode space ($B + C = B^1 + C^1 = B^2 + C^2$), and X is the thickness of the electroconductive adhesive layer prior to connection.